EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S194	10	(((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with (lack $3 insufficient deficient inadequate scarce improper low little poor defect$3) near3 (volume amount quantity portion) with (((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) and (re$1deposit$3 re$1print$3 re$1apply $3 ((reiterat$3 repeat $3 again add$3 additional add$1on supplement$2) near3 (print$3 jet$4 solder$3 apply$3 dispens$3)))	USPAT; EPO; JPO	OR	ON	2009/05/24 21:29
S195	5	(((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with	USPAT; EPO; JPO	OR	ON	2009/05/24 21:36

		(((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) same (lack$3 insufficient deficient inadequate scarce improper low little poor defect$3) near3 (volume amount quantity portion) and (re$1deposit$3 re $1print$3 re$1apply$3 ((reiterat$3 repeat$3 again add$3 additional add$1on supplement $2) near3 (print$3 jet $4 solder$3 apply$3 dispens$3))) not S194				
S196	8	(((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with (lack $3 insufficient deficient inadequate scarce improper low little poor defect$3) near3 (volume amount quantity portion) with (((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) not S194 not S195	USPAT; EPO; JPO	OR	ON	2009/05/24 21:37

| S197 | 16 | (((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with (((metal$3 conduct$3 viscous) near3 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) same (lack$3 insufficient deficient inadequate scarce improper low little poor defect$3) near3 (volume amount quantity portion) not S194 not S195 not S196 | USPAT; EPO; JPO | OR | ON | 2009/05/24 21:39 |
| S198 | 0 | (((metal$3 conduct$3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with (lack $3 insufficient deficient inadequate scarce improper low little poor defect$3) near3 (volume amount quantity portion) with (((metal$3 conduct$3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution | USPAT; EPO; JPO | OR | ON | 2009/05/24 21:45 |

		adhesive glue)) solder $3) and (re$1deposit$3 re$1print$3 re$1apply $3 ((reiterat$3 repeat $3 again add$3 additional add$1on supplement$2) near3 (print$3 jet$4 solder$3 apply$3 dispens$3))) not S194 not S195 not S196 not S197				
S199	92	(((metal$3 conduct$3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with (volume amount quantity portion) with (((metal$3 conduct$3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) and (re$1deposit$3 re$1print$3 re$1apply $3 ((reiterat$3 repeat $3 again add$3 additional add$1on supplement$2) near3 (print$3 jet$4 solder$3 apply$3 dispens$3))) not S194 not S195 not S196 not S197	USPAT; EPO; JPO	OR	ON	2009/05/24 21:49

S200	168	(((metal$3 conduct$3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) with ((screen stencil squeegee) near3 print$3) and (detect$3 recogniz$3 inspect$3 evaluat$3 analyz$3 calculat$3 determin$3) with (((metal$3 conduct$3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder $3) and (re$1deposit$3 re$1print$3 re$1apply $3 ((reiterat$3 repeat $3 again add$3 additional add$1on supplement$2) near3 (print$3 jet$4 solder$3 apply$3 dispens$3))) with (((metal$3 conduct $3 viscous bond$3) near4 (material substance paste medium ink slurry liquid solution adhesive glue)) solder$3) not S194 not S195 not S196 not S197 not S199	USPAT; EPO; JPO	OR	ON	2009/05/24 22:07
S201	1	"5714195".pn.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2009/05/24 22:24
S202	28	("4313124" | "4345262" | "4459600" | "4463359" | "4558333" | "4608577" | "4723129" | "4740796" | "4991030" | "5032713" | "5246804" | "5281450" | "5340619").PN. OR ("5714195").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/05/24 22:25

| S203 | 12 | ("20010040290" \| "20020031868" \| "5212216" \| "5908317" \| "6100475" \| "6145011" \| "6159837" \| "6165885" \| "6264097" \| "6348401").PN. OR ("6468893").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2009/05/24 22:35 |
| S204 | 5 | ("5693559").URPN. | USPAT | OR | ON | 2009/05/24 22:35 |

5/25/09 10:58:35 PM
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